



TAI-SAW TECHNOLOGY CO., LTD.

No. 3, Industrial 2nd Rd., Ping-Chen Industrial District,
Taoyuan, 324, Taiwan, R.O.C.

TEL: 886-3-4690038 FAX: 886-3-4697532

E-mail: tstsales@mail.taisaw.com Web: www.taisaw.com

Product Specifications Approval Sheet

Product Name: DR Filter 5665MHz (BW=370MHz) 8.46x3.0x3.45

TST Parts No.: TR0011A

Vendor Parts No.: _____

Company: _____
Division: _____
Approved by : _____
Date: _____

Checked by: _____ Hong Pu Lin *Hong Pu Lin*

Approval by: _____ Andy Yu *Andy Yu*

Date: _____ 06 / 20 / 2018

1. Customer signed back is required before TST can proceed with sample build and receive orders.
2. Orders received without customer signed back will be regarded as agreement on the specifications.
3. Any specifications changes must be approved upon by both parties and a new revision of specifications shall be released to reflect the changes.



TAI-SAW TECHNOLOGY CO., LTD.

No.3, Industrial 2nd Rd., Ping-Chen Industrial District, Taoyuan, Taiwan, R.O.C.

TEL: 886-3-4690038 FAX: 886-3-4697532

E-mail: tstsales3@mail.taisaw.com Web: www.taisaw.com

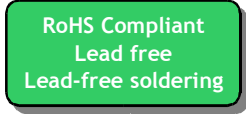
DR Filter 5665MHz 370MHz BW

MODEL NO.: TR0011A

REV. NO.1

A. MAXIMUM RATING:

1. Operating temperature range: -40°C to 85°C
2. Storage temperature range: -40°C to 85°C
3. Input Power Level : 1W
4. Input/Output Impedance:50 Ohm
5. Moisture Sensitivity Level: Level(MSL1)

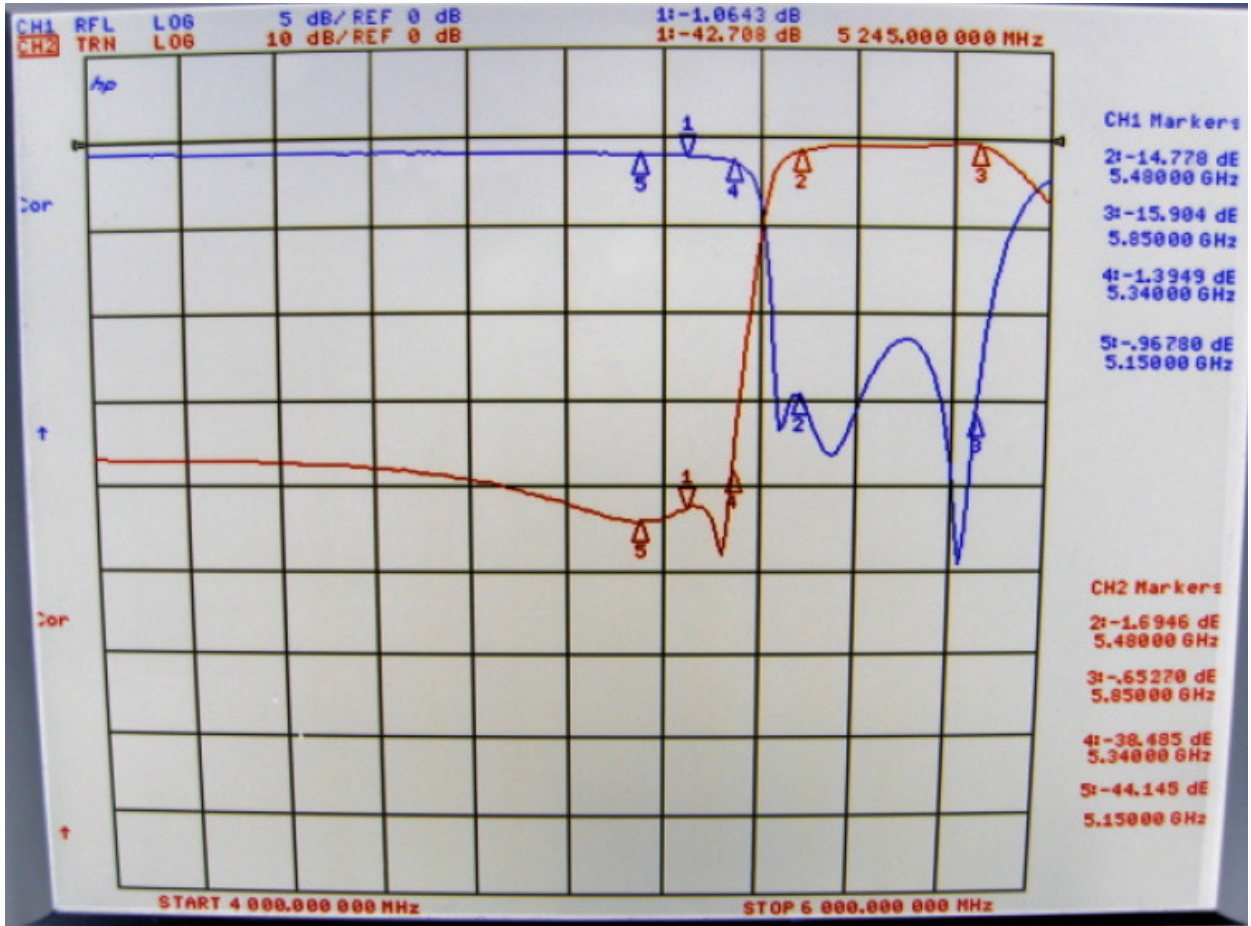


Electrostatic Sensitive Device

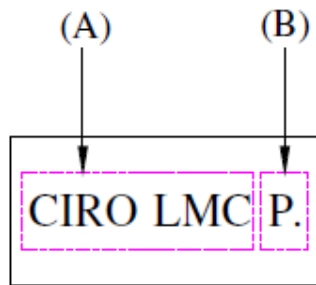
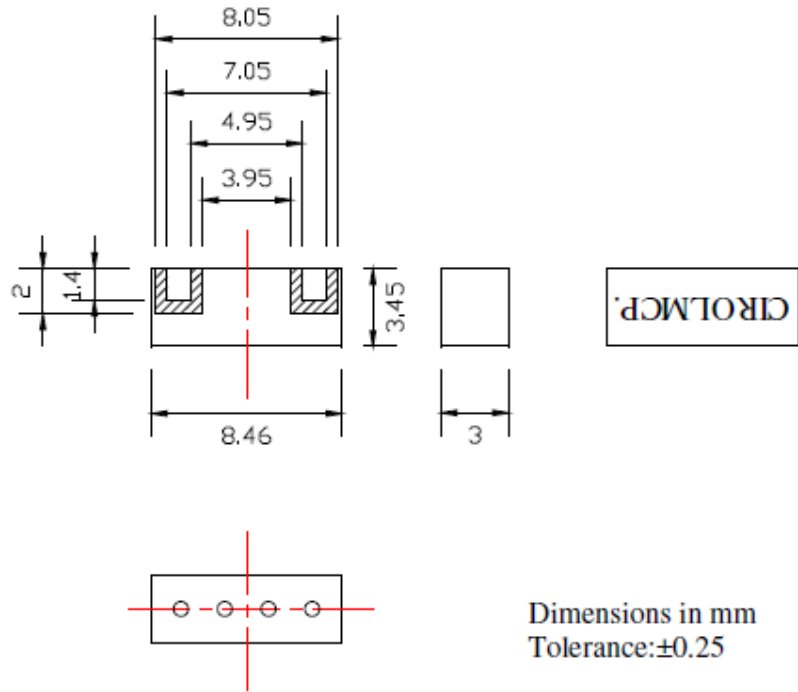
B. CHARACTERISTICS:

Item	Unit	typ	Spec.
Center frequency, F_c	MHz	5665	
Insertion Loss, (5480~5850MHz)	dB	1.5	2.0max
Passband Ripple (5480~5850MHz)	dB	0.8	1.5max
Return Loss (5480~5850MHz)	dB	12	10min
Specifies the absolute value of Attenuation			
5150~5340MHz	dB	38	35min

C. FREQUENCY CHARACTERISTICS:



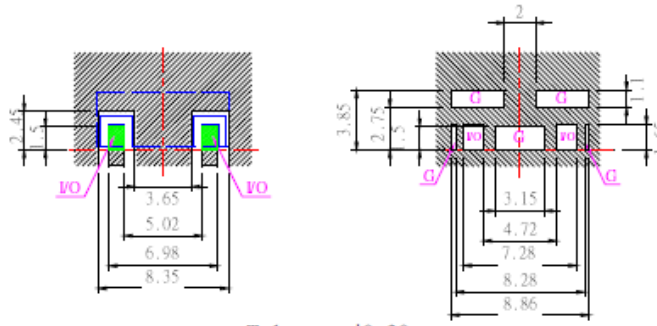
D. OUTLINE DRAWING:



(B) Product name : CIRO LMC
 (C) Year/Month : Please refer to the Table-1

(Table-1)

Year	Month	Code	Year	Month	Code	Year	Month	Code	Year	Month	Code
2012 2016 2020 2024	1	A	2013 2017 2021 2025	1	N	2014 2018 2022 2026	1	A.	2015 2019 2023 2027	1	N.
	2	B		2	P		2	B.		2	P.
	3	C		3	Q		3	C.		3	Q.
	4	D		4	R		4	D.		4	R.
	5	E		5	S		5	E.		5	S.
	6	F		6	T		6	F.		6	T.
	7	G		7	U		7	G.		7	U.
	8	H		8	V		8	H.		8	V.
	9	J		9	W		9	J.		9	W.
	10	K		10	X		10	K.		10	X.
	11	L		11	Y		11	L.		11	Y.
	12	M		12	Z		12	M.		12	Z.



Tolerance ± 0.20
 I/O : Input/Output
 G : Ground



Electrode



Solder Resist

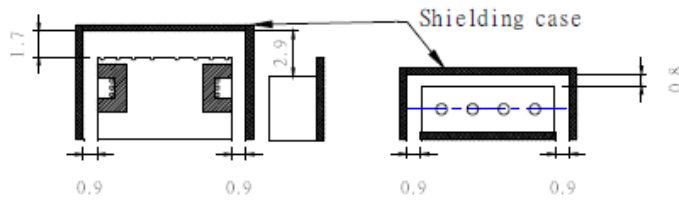


I/O Pads must be connected to lines with 50Ω impedance. In the application a termination of 50Ω must be realized.

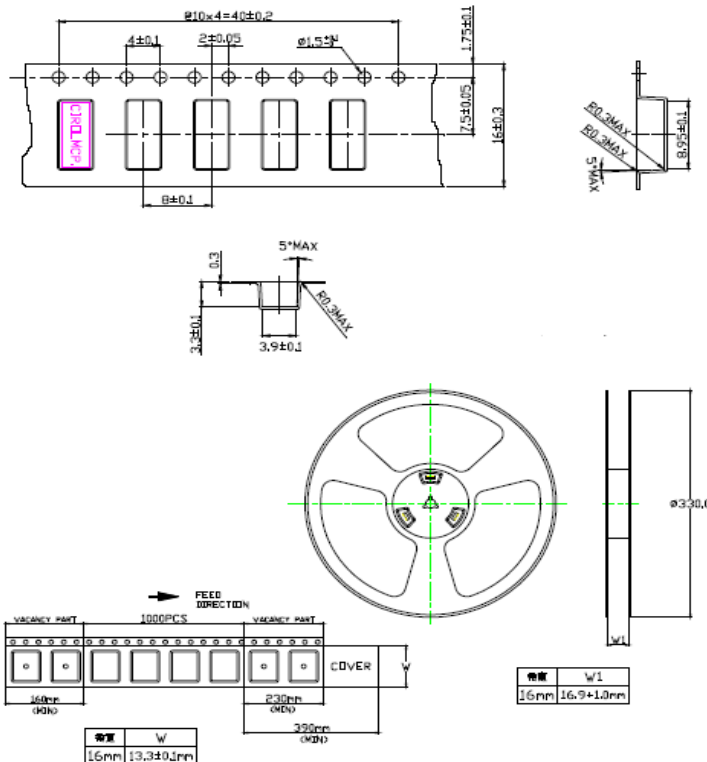


Solder LAND

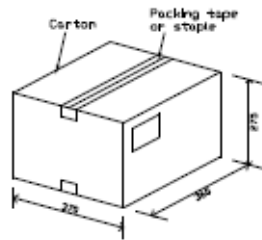
Shielding case layout guide (min)



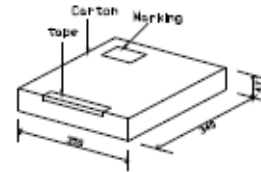
F. PACKING:



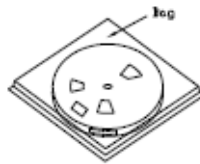
1. Outer Carton
Quantity:5000PCS



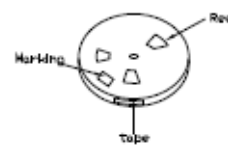
2. Inner Carton
Quantity:1000PCS



3. Bag
Quantity:1000PCS



4. Taping
Quantity:1000PCS



Unit:mm

F. RECOMMENDED REFLOW PROFILE:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150°C 200°C 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217°C 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260°C 3 second
RAMP-DOWN	Rate	6°C / second max.
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

The graphic shows temperature profile for component assembly process in reflow ovens

